

## FEATURES

- | Size Design  $\Phi 5.5 \times 6.0 \text{mm}$

---

- | High Current Handling Capability 5,000A @ 8/20  $\mu\text{s}$

---

- | Low Capacitance and Insertion Loss

---

- | Quick Response and Long Service Life

---

- | Moisture sensitivity level: Level 1

---



 $\Phi 5.5 \times 6.0 \text{mm}$ 

## APPLICATION INFORMATION

- | Communication equipment.

---

- | Repeaters, Modems

---

- | Telephone Interface, Line cards.

---


- | Data communication equipment.

---




Schematic Symbol

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Limit	Unit
DC Blocking Voltage 1)	100V/s	336-504	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq$ 900	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq$ 850	V
Impulse Discharge Current 2)	8/20 $\mu$ s $\pm$ 5times	5	KA
Insulation Resistance	DC=100V	$\geq$ 1	G $\Omega$
Capacitance at 1MHz	V <sub>DC</sub> =0.5V	$\leq$ 1	pF
Operating and Storage Temperature		-40~125	$^{\circ}$ C

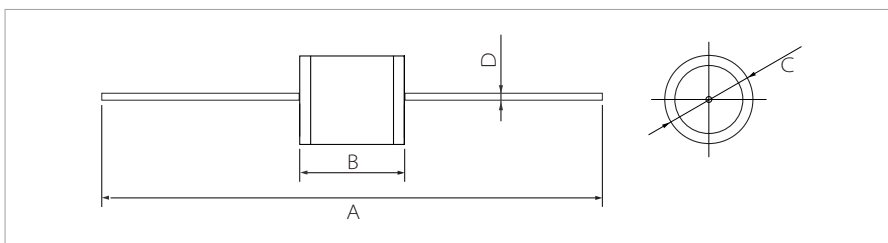
1) In ionized mode

2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

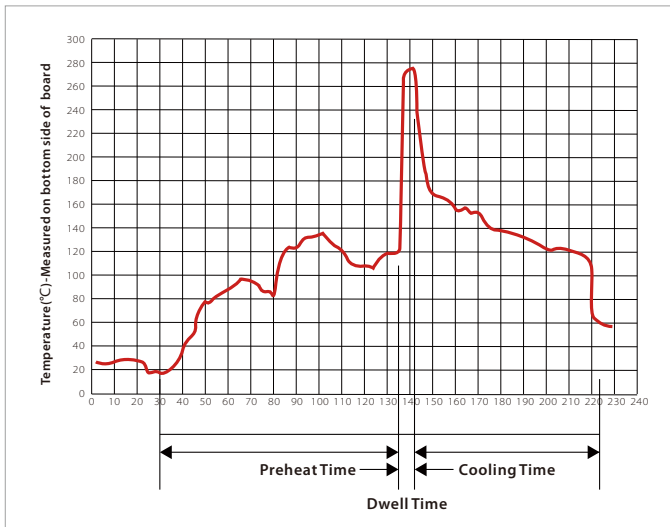
Testing items	Technical standards
High Temperature Storage Test	Temperature: 125 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $\pm$ 5 $^{\circ}$ C; Time of dip soldering: 10s,1time

## PRODUCT DIMENSIONS



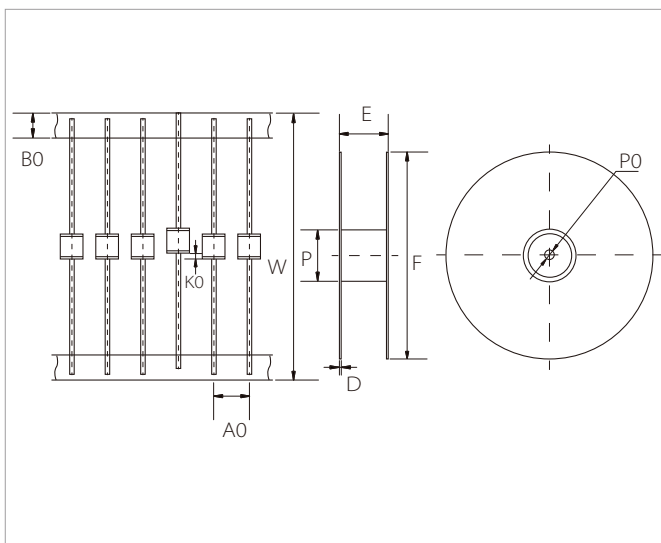
Ref.	Outline Dimensions
	Millimeters
A	62 $\pm$ 2
B	6 $\pm$ 0.2
C	$\Phi$ 5.5 $\pm$ 0.2
D	$\Phi$ 0.8

## WAVE SOLDERING




Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

## TAPE AND REEL SPECIFICATION



Ref.	Dimensions	
	Millimeters	Inches
W	65±2	2.559±0.079
A0	10±0.5	0.394±0.020
B0	6±1	0.236±0.012
K0	1.2 Max.	0.47 Max.
D	2.5±0.5	0.098±0.020
F	340±2	13.39±0.079
E	73±2	2.874±0.079
P	82±2	3.228±0.079
P0	Φ16±1	Φ0.63±0.039

## ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs	
			Reel	Carton
SG2R05B420	Φ5.5*6.0mm	 SG420 05	1000	4000

**Headquarters**

No.3387 Shendu Road Pujiang  
I&E Park  
Minhang Shanghai China  
201000

**Hotline**

400-021-5756

**Web**

<https://www.semiware.com>

**Sales Center**

Tel: 86-21-3463-7458  
Email: [sales18@semiware.com](mailto:sales18@semiware.com)

**Customer Service**

Tel: 86-21-5484-1001  
Email: [sales17@semiware.com](mailto:sales17@semiware.com)

**Technical Support**

Tel: 86-21-3463-7654  
Email: [fae01@semiware.com](mailto:fae01@semiware.com)

**Complaint & Suggestions**

Tel: 86-21-3463-7172  
Ext: 8868  
Email: [cs03@semiware.com](mailto:cs03@semiware.com)

**By QR Code**

Website



Wechat

To find your local partner within Semiware's global network: [www.semiware.com](http://www.semiware.com)

© 2022 Semiware Semiconductor Inc.

The content of this document has been carefully checked and understood. However, neither Semiware nor its subsidiaries assume any liability whatsoever for any errors or inaccuracies of this document and the consequences thereof. Published specifications are subject to change without notice. Product suitability for any area of application must ultimately be determined by the customer. In all cases, products must never be operated outside their published specifications. Semiware does not guarantee the availability of all published products. This disclaimer shall be governed by substantive Chinese law and resulting disputes shall be settled by the courts at the place of business of Semiware. Latest publications and a complete disclaimer can be downloaded from the Semiware website. All trademarks recognized.